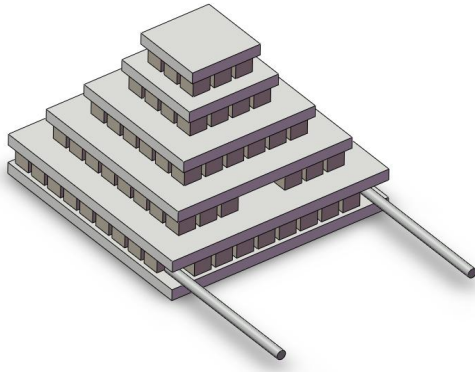


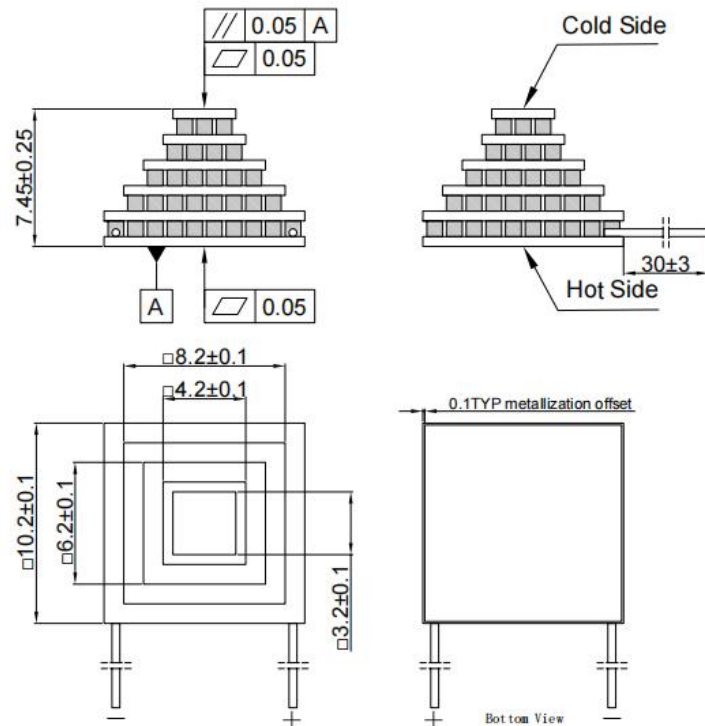


PERFORMANCE CHARACTERISTICS

N_2 @ $T_h = 27^\circ C$

$\Delta T_{max}(K)$	115.4	± 5
$Q_{max}(W)$	1.02	± 0.05
$I_{max}(A)$	1.9	± 0.1
$U_{max}(V)$	5.13	± 0.25
ACR(Ohm)	2.66	± 0.3

MECHANICAL CHARACTERISTICS



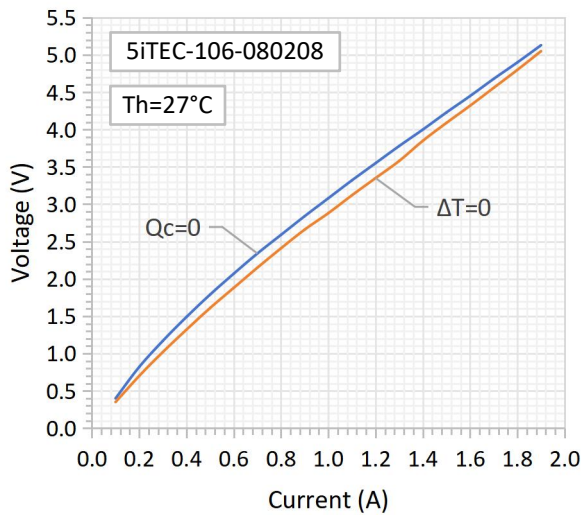
-all dimensions are in mm;

MANUFACTURING SPECIFICATIONS

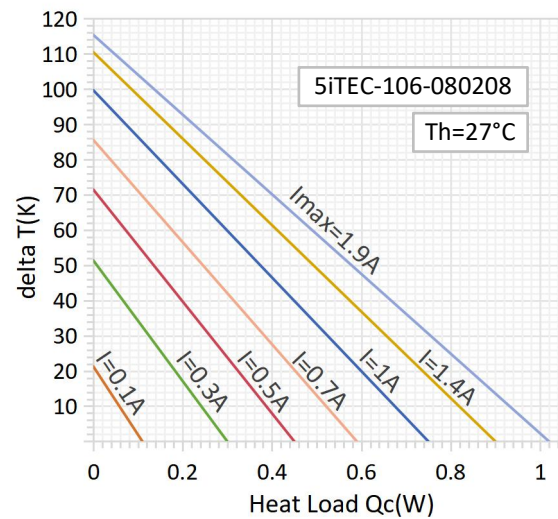
1. TEC assembly solder - SnBi (m.p. $230^\circ C$);
2. Substrates material - ALN;
 - a) cold side finishing - no metallization;
 - b) hot side finishing - metallized , 0.2 μm Au finishing layer;
3. Terminal contacts - dia.0.4mm solid copper wire tinned with SnBi;
4. Max. short time processing temperature - $200^\circ C$;
5. Product is RoHS and REACH compliant;
6. TEC is Telcordia GR468 and MIL-STD-883 compliant

TYPICAL PERFORMANCE GRAPHS

Voltage-Current characteristic



ΔT — $F(Q_c)$



-other performance graphs are available on request;

Logbook

NO.	REVISION	Date	Version
1	Initial version	2025.03.05	Rev00